CPI1008KR47R-10

UNCONTROLLED DOCUMENT

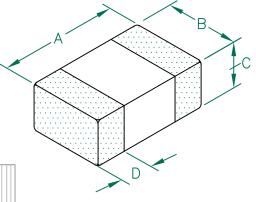
PHYSICAL DIMENSIONS:

A 2.50 [.098] ± 0.20[.008]

B 2.00 [.079] ± 0.20[.008]

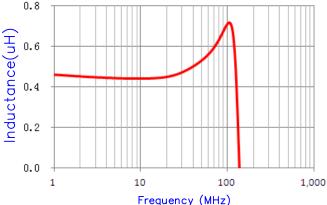
C 0.90 [.035] ± 0.10[.004]

D 0.60 [.024] ± 0.20[.008]

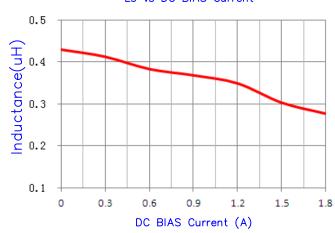




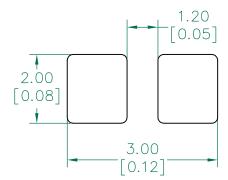
Ls vs Frequency



Ls vs DC BIAS Current



LAND PATTERNS FOR REFLOW SOLDERING



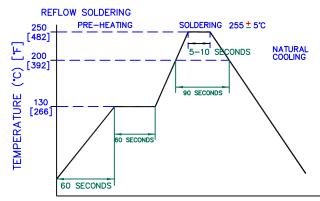
(For wave soldering. add 0.763 [0.030] to this dimension)

ELECTRICAL CHARACTERISTICS: $(\mu H) \otimes 1MHz$ DCR (Ω) I (Max) ± 20% ± 25% Nom 0.470 0.0700 0.376 0.0525 Min 0.0875 0.564 1800mA Max

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS





		DIMENSIONS ARE IN mm [INCHE	This print is the property of Lair							
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ı					PROJECT/PART NUMBER:	T	REV	PART T	PE:	DRAWN BY:
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ł	В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13							
ŀ						SCA	LE: N	TS	SHEET:	
	Α	ORIGINAL DRAFT	03/01/11	QU	CAD #	TOO	. #	-	4	
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